

AMENDMENTS TO THE CLAIMS

1-22. (cancelled)

5 23. (previously presented): A light emitting diode, comprising at least:

a substrate;

a reflective layer formed over the substrate;

a first reaction layer formed over said reflective layer;

a transparent adhesive layer formed over said first reaction layer;

10 a second reaction layer formed over said transparent adhesive layer;

and an LED stack formed over said second reaction layer;

wherein each of the first and second reaction layers is formed to enhance an adhesion provided by the transparent adhesive layer;

15 wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and

wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

20 24. (previously presented): A light emitting diode according to claim 23, further comprising a transparent conductive layer between said second reaction layer and said LED stack.

25 25. (previously presented): A light emitting diode according to claim 23, wherein said reflective layer is a reflective metal layer.

26. (cancelled)

30 27. (previously presented): A light emitting diode according to claim 25, wherein said reflective metal layer comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.

28-43. (cancelled)

44. (previously presented): A light emitting diode, comprising at least:

- 5 a reflective means;
 a first reaction layer formed over said reflective means;
 a transparent adhesive layer formed over said first reaction layer;
 a second reaction layer formed over said transparent adhesive layer; and
 an LED stack formed over said second reaction layer;
- 10 wherein the first and second reaction layers enhance adhesion provided by the
 transparent adhesive layer,
 wherein said transparent adhesive layer comprises at least a material selected from
 the group consisting of polyimide (PI), benzocyclobutene (BCB), and
 perfluorocyclobutane (PFCB); and
- 15 wherein each said first and second reaction layers comprises at least a material
 selected from the group consisting of SiNx, Ti, and Cr.

45. (previously presented): A light emitting diode, comprising at least:

- a substrate;
- 20 a reflective layer disposed on the substrate;
 a first reaction layer formed on said reflective layer;
 a transparent adhesive layer formed directly on said first reaction layer, said
 first reaction layer adhering to the transparent adhesive layer;
 a second reaction layer formed directly on said transparent adhesive layer, said
- 25 second reaction layer adhering to the transparent adhesive layer; and
 an LED stack formed over said second reaction layer,
 wherein said transparent adhesive layer comprises at least a material selected from
 the group consisting of polyimide (PI), benzocyclobutene (BCB), and
 perfluorocyclobutane (PFCB); and
- 30 wherein each said first and second reaction layers comprises at least a material
 selected from the group consisting of SiNx, Ti, and Cr.

46. (cancelled)

47. (previously presented): A light emitting diode according to claim 45, further comprising a transparent conductive layer between said second reaction layer and said LED stack.

48. (previously presented): A light emitting diode according to claim 45, wherein said reflective layer is a reflective metal layer.

49. (previously presented): A light emitting diode according to claim 48, wherein said reflective metal layer comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.

50-51. (cancelled)

52 (new): A light emitting diode according to claim 23, wherein said reflective layer is a reflective oxide layer.

53 (new): A light emitting diode according to claim 52, wherein said reflective oxide layer comprises at least a material selected from the group consisting of SiNx, SiO₂, Al₂O₃, TiO₂, and MgO.